



## Description

### JMT P-channel Enhancement Mode Power MOSFET

#### Features

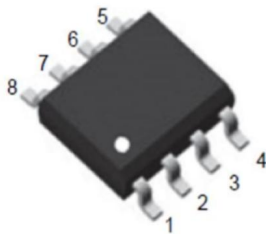
- $V_{DS} = -30V$ ,  $I_D = -9A$   
 $R_{DS(ON)} < 25m\Omega @ V_{GS} = -10V$   
 $R_{DS(ON)} < 38m\Omega @ V_{GS} = -4.5V$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead free product is acquired

#### Application

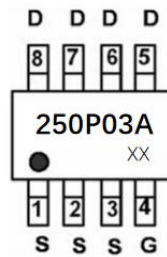
- PWM Applications
- Load Switch
- Power Management



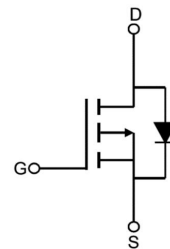
*100% UIS TESTED!*  
*100% ΔVds TESTED!*



SOP-8 top view



Marking and pin Assignment



Schematic Diagram

## Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
250P03A	JMTP250P03A	TAPING	SOP-8	13inch	4000	48000

## Absolute Maximum Ratings ( $T_A = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Max.	Units
$V_{DSS}$	Drain-Source Voltage	-30	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_A = 25^\circ C$	-9
		$T_A = 100^\circ C$	-5.9
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>	-36	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>note2</sup>	25	mJ
$P_D$	Power Dissipation	$T_A = 25^\circ C$	3.3
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	38	$^\circ C/W$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ C$



## Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise specified)

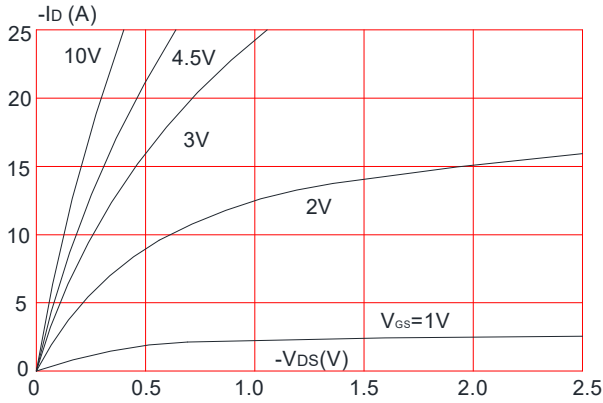
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> = -250μA	-30	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V,	-	-	-1	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-1.0	-1.5	-2.5	V
R <sub>DS(on)</sub>	Static Drain-Source on-Resistance <small>Note3</small>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -9A	-	19	25	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -5A	-	27	38	
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V, f = 1.0MHz	-	1200	-	pF
C <sub>oss</sub>	Output Capacitance		-	155	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	139	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = -15V, I <sub>D</sub> = -8A, V <sub>GS</sub> = -10V	-	52	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	9.8	-	nC
Q <sub>gd</sub>	Gate-Drain("Miller") Charge		-	8.3	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> = -15V, I <sub>D</sub> = -1A, V <sub>GS</sub> =-10V, R <sub>GEN</sub> =6Ω	-	13	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	15	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	198	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	98	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	-9	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-36	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = -9A	-	-0.8	-1.2	V

- Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature  
 2. EAS condition: T<sub>J</sub>=25°C, V<sub>DD</sub>=-15V, V<sub>G</sub>=-10V, R<sub>G</sub>=25Ω, L=0.5mH, I<sub>AS</sub>=-10A  
 3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

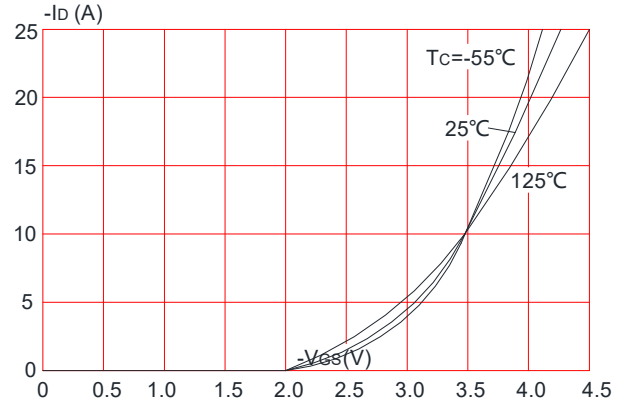


## Typical Performance Characteristics

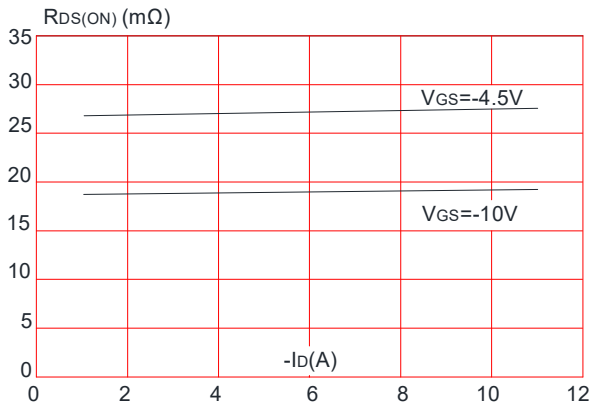
**Figure 1: Output Characteristics**



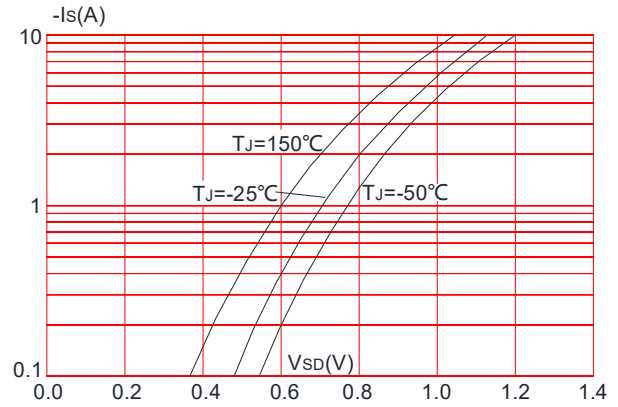
**Figure 2: Typical Transfer Characteristics**



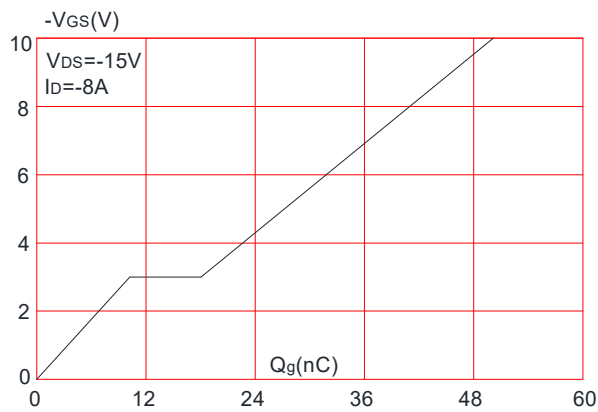
**Figure 3: On-resistance vs. Drain Current**



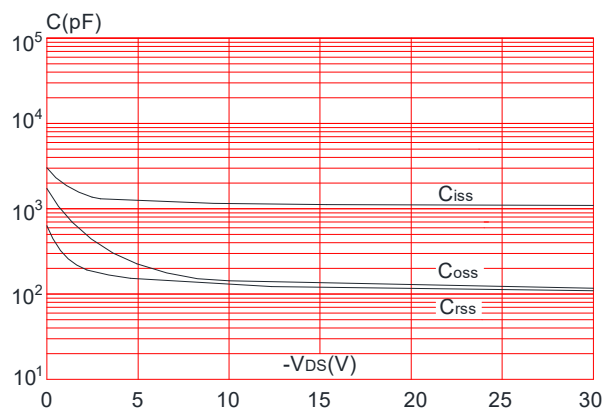
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**

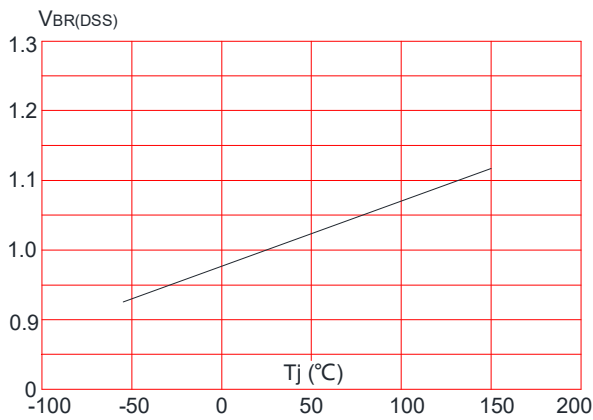


**Figure 6: Capacitance Characteristics**

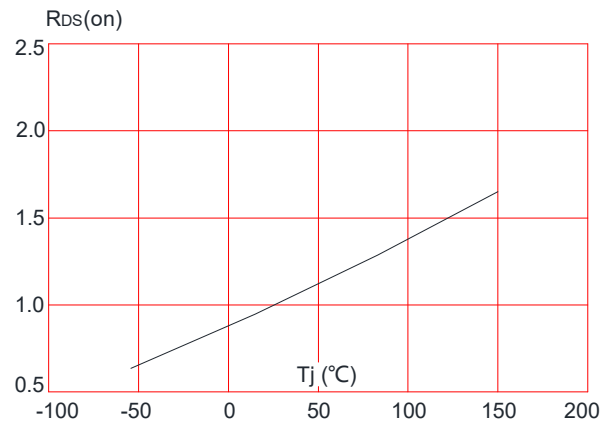




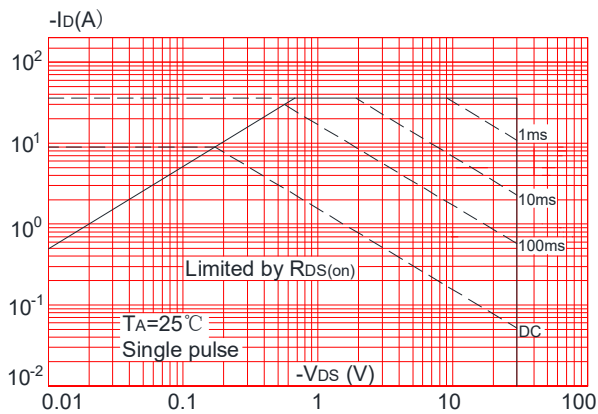
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



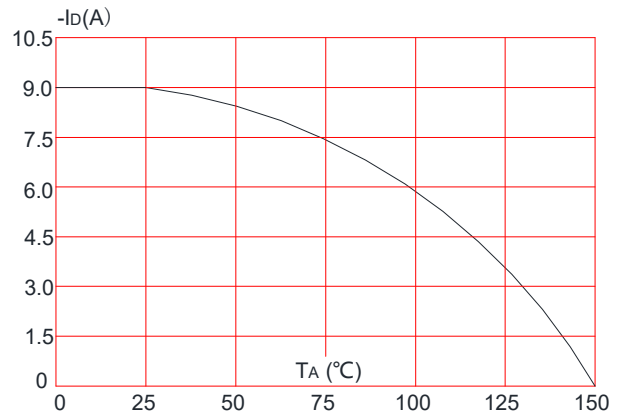
**Figure 8:** Normalized on Resistance vs. Junction Temperature



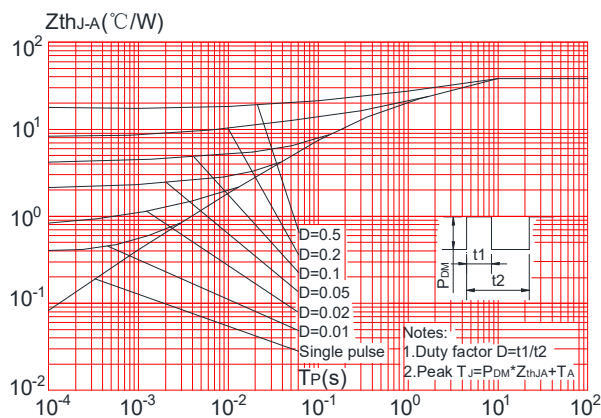
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



## Test Circuit

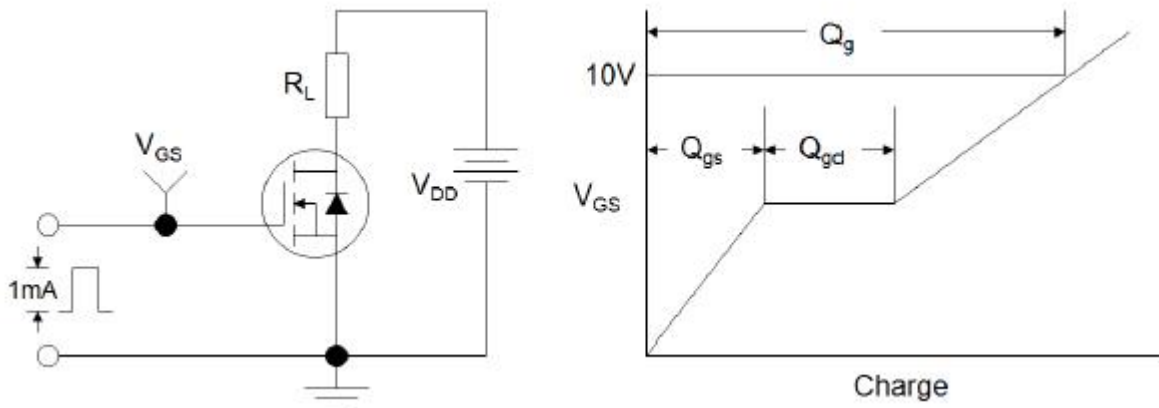


Figure1:Gate Charge Test Circuit & Waveform

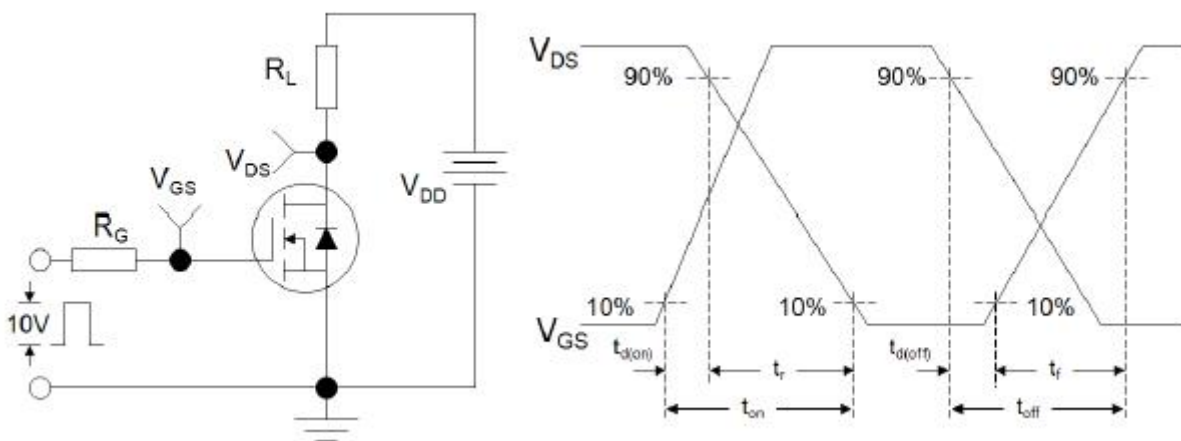


Figure 2: Resistive Switching Test Circuit & Waveforms

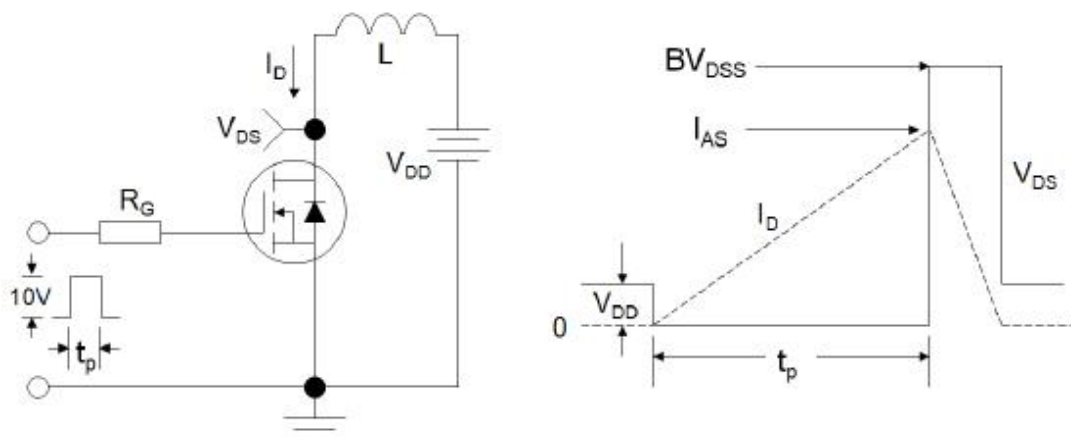
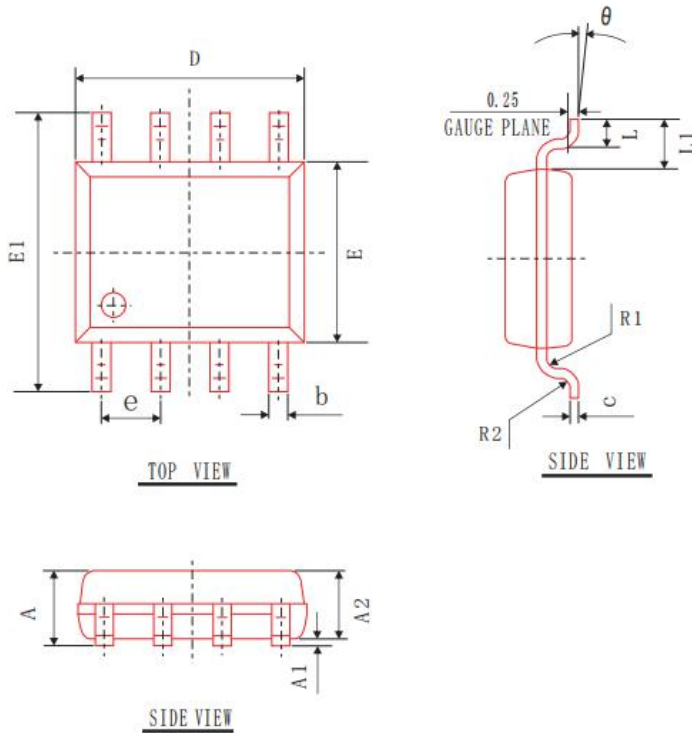


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms



## Package Mechanical Data-SOP-8



COMMON DIMENSIONS  
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	1.40	1.60	1.80
A1	0.05	0.15	0.25
A2	1.35	1.45	1.55
b	0.30	0.40	0.50
c	0.153	0.203	0.253
D	4.80	4.90	5.00
E	3.80	3.90	4.00
E1	5.80	6.00	6.20
L	0.45	0.70	1.00
$\theta$	2°	4°	6°
L1	1.04 REF		
e	1.27 BSC		
R1	0.07 TYP		
R2	0.07 TYP		

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